## 505674619 09/16/2019

## PATENT ASSIGNMENT COVER SHEET

EPAS ID: PAT5721426

Electronic Version v1.1
Stylesheet Version v1.2

 SUBMISSION TYPE:
 NEW ASSIGNMENT

 NATURE OF CONVEYANCE:
 ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
Chin-Hung Chen	09/13/2019
Ssu-I Fu	09/13/2019
Chih-Kai Hsu	09/13/2019
Chun-Ya Chiu	09/13/2019
Chia-Jung Hsu	09/13/2019
Yu-Hsiang Lin	09/13/2019

#### **RECEIVING PARTY DATA**

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Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN

#### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	16572556

#### **CORRESPONDENCE DATA**

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ATTORNEY DOCKET NUMBER: NAUP3497USA

NAME OF SUBMITTER: SIBYL YU

SIGNATURE: /SIBYL YU/

DATE SIGNED: 09/16/2019

**Total Attachments: 12** source=3585148#page1.tif

PATENT 505674619 REEL: 050393 FRAME: 0821



#### Title of Invention:

# SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF

As the below named inventor, I here This declaration is directed to:	by declare that:		
☑ The attached application, or			
☐ United States application nu	ımber	_filed on	, or
☐ PCT international applicatio	n number	filed on	
The above-identified application was	made or authorized to be made	by me.	
I believe that I am the original invent application.	or or an original joint inventor of a	claimed invention in the	
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In consideration of the payment by	UNITED MICROELECTRON	NICS having a postal add	lress of
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I hereby sell, assign and transfer to A the entire right, title and interest in ar invention as above-identified applica invention by the above application or substitutes, or extensions thereof, ar	nd to any and all improvements w tion and, in and to, all Letters Pat any continuations, continuation-i	hich are disclosed in the ent to be obtained for said in-part, divisions, renewals.	EE
I hereby covenant that no assignmer entered into which would conflict with	nt, sale, agreement or encumbran n this assignment;	ce has been or will be made	or
I further covenant that ASSIGNEE w and documents relating to said inven known and accessible to I and will te related thereto and will promptly exec	ition and said Letters Patent and stify as to the same in any interfe	legal equivalents as may be rence, litigation proceeding	ets
representatives any and all papers, in maintain, issue and enforce said app equivalents thereof which may be ne IN WITNESS WHEREOF, I have her	lication, said invention and said L cessary or desirable to carry out	etters Patent and said	
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NPO#NAU-P3497-USA:0 CUST#UMCD-2019-0289

LEGAL NA	ME OF INVENTOR(ASSI	3NOR)		
Inventor:	Chin-Hung Chen		Date:	SEP 1 3 2019
Signature:	Chin-Hung	chen	**************************************	
	1			

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NPO#NAU-P3497-USA:0 CUST#UMCD-2019-0289

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NPO#NAU-P3497-USA:0 CUST#UMCD-2019-0289

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Ssu-I Fu Date: SEP 1 3 2019

Signature: 444 - 7 74

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NPO#NAU-P3497-USA:0 CUST#UMCD-2019-0289

F#NPO-P0002E-US1201 DSB0-108U020620

#### Title of Invention:

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NPO#NAU-P3497-USA:0 CUST#UMCD-2019-0289

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Chih-Kai Hsu

Signature: Chih-Kai Hsu

Date: SEP 1 3 2019

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NPO#NAU-P3497-USA:0 CUST#UMCD-2019-0289

## Title of Invention:

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Page 7 of 12

NPO#NAU-P3497-USA:0 CUST#UMCD-2019-0289

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Chun-Ya Chiu Date: SEP 1 3 2019

Signature: Chuh (a Chiu

Page 8 of 12

NPO#NAU-P3497-USA:0 CUST#UMCD-2019-0289

F#NPO-P0002E-US1201 DSB0-108U020620

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Page 9 of 12

NPO#NAU-P3497-USA:0 CUST#UMCD-2019-0289

LEGAL NAME OF INVENTOR(ASSIGNOR)						
Inventor:	Chia-Jung Hsu	Date:	SEP	1	3	2019
Signature:	Chia-Jung Hsu					

Page 10 of 12

NPO#NAU-P3497-USA:0 CUST#UMCD-2019-0289

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NPO#NAU-P3497-USA:0 CUST#UMCD-2019-0289

Inventor: Yu-Hsiang Lin

Signature: 

M Stany Jin

NPO#NAU-P3497-USA:0 CUST#UMCD-2019-0289 Page 12 of 12

F#NPO-P0002E-US1201 DSB0-108U020620

PATENT REEL: 050393 FRAME: 0834

**RECORDED: 09/16/2019**